v 1.0 17.03.2014

SMB1N-850D

- Infrared High Power LED
- 850 nm, 650 mW
- SMD package, PA9T
- Dimension: 5.0 x 5.2 x 1.0 mm
- Viewing Angle: 124°





Description

SMB1N-850D is a surface mount AlGaAs High Power LED with a typical peak wavelength of 850 nm and radiation of 650 mW. It comes in SMD package (PA9T) with silver plated soldering pads (lead free solderable), copper heat sink, and molded with silicone resin.

Maximum Ratings (TCASE=25°C)

Downwoodow	Cumbal	Val	Heit	
Parameter	Symbol	Min.	Max.	Unit
Power Dissipation	P_D		2500	mW
Forward Current	IF		1000	mA
Pulse Forward Current *1	I _{FP}		3000	mA
Reverse Voltage	V _F		5	V
Thermal Resistance	R_{THJA}		10	K/W
Junction Temperature	T_J		120	°C
Operating Temperature	T_{CASE}	- 40	+ 100	°C
Storage Temperature	T _{STG}	- 40	+ 100	°C
Lead Solder Temperature *2	T_{SLD}		+ 250	°C

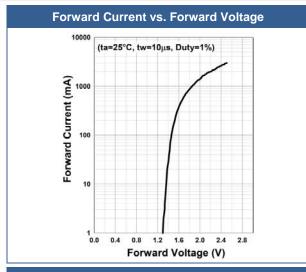
Electro-Optical Characteristics $(T_{CASE}=25^{\circ}C)$

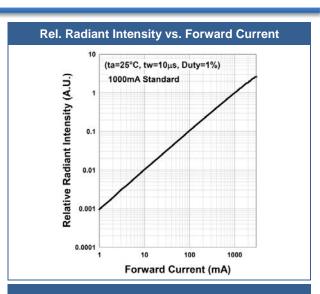
Parameter	Symbol	Conditions	Min.	Values Typ.	Max.	Unit
Peak Wavelength	λ_P	I _F =1000mA	840	850		nm
Half Width	$\Delta \lambda$	I _F =1000mA		37		nm
Forward Voltage	V_F	$I_F=350mA$		1.5	1.9	V
	V_F	I _F =1000mA		2.1	2.5	
	V_{FP}	$I_{FP}=3A$		2.5		
Radiated Power *1	Po	I _F =1000mA	450	650		mW
		$I_{FP}=3A$		1800		
Radiant Intensity *2	IE	I _F =1000mA		210		mW/sr
		$I_{FP}=3A$		600		
Viewing Angle	φ	I _F =100mA		124		deg.
Rise Time	t_R	I _F =1000mA		50		ns
Fall Time	tϝ	I _F =1000mA		50		ns

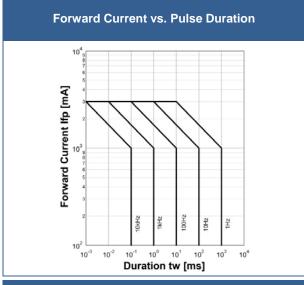
^{*&}lt;sup>1</sup> duty=1%, pulse width = 10 μs *² must be completed within 5 seconds

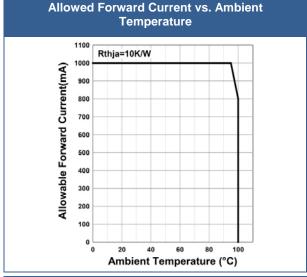
 ^{*1} measured by S3584-08
*2 measured by CIE127-2007 Condition B

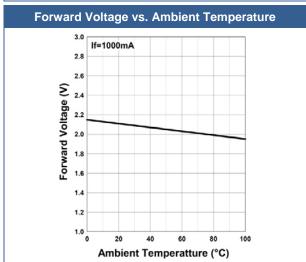
Typical Performance Curves

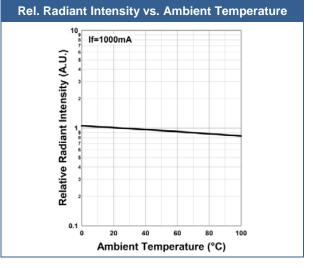










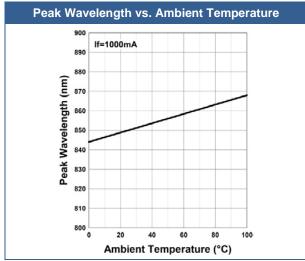


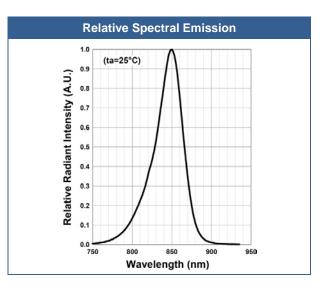


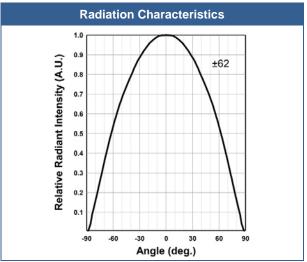
ROITHNER LASERTECHNIK GmbH

WIEDNER HAUPTSTRASSE 76 IO40 VIENNA AUSTRIA TEL. +43 I 586 52 43 -0. FAX. -44 OFFICE@ROITHNER-LASER.COM

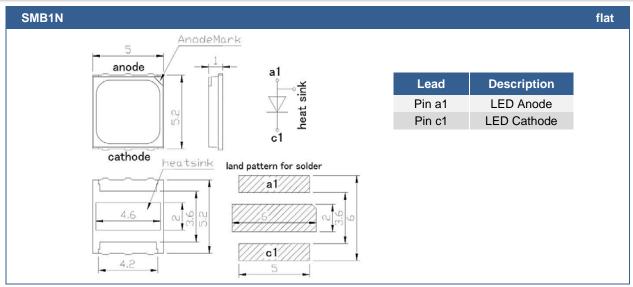








Outline Dimensions



All Dimensions in mm

Precautions

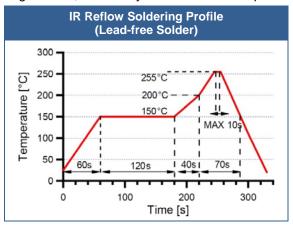
Soldering:

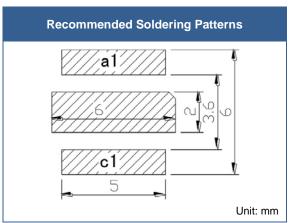
- · Do avoid overheating of the LED
- Do avoid electrostatic discharge (ESD)
- Do avoid mechanical stress, shock, and vibration
- Do only use non-corrosive flux
- Do not apply current to the LED until it has cooled down to room temperature after soldering

Recommended soldering conditions:

This LED is designed to be reflow soldered on to a PCB. If dip soldered or hand soldered, its reliability cannot be guarantee.

Nitrogen reflow soldering is recommended. Air flow soldering conditions can cause optical degradation, caused by heat and/or atmosphere.





4

Above table specifies the maximum allowed duration and temperature during soldering. It is strongly advised to perform soldering at the shortest time and lowest temperature possible.

Cleaning:

Cleaning with isopropyl alcohol, propanol, or ethyl alcohol is recommended

DO NOT USE acetone, chloroseen, trichloroethylene, or MKS

DO NOT USE ultrasonic cleaners

Static Electricity:

LEDs are sensitive to electrostatic discharge (ESD). Precautions against ESD must be taken when handling or operating these LEDs. Surge voltage or electrostatic discharge can result in complete failure of the device.

Radiation:

During operation these LEDs do emit **high intensity light**, which is hazardous to skin and eyes, and may cause cancer. Do avoid exposure to the emitted light. **Protective glasses are recommended**. It is further advised to attach a warning label on products/systems.

Operation:

Do only operate LEDs with a current source.

Running these LEDs from a voltage source will result in complete failure of the device. Current of a LED is an exponential function of the voltage across it. Usage of current regulated drive circuits is mandatory.

The above specifications are for reference purpose only and subjected to change without prior notice

[©] All Rights Reserved